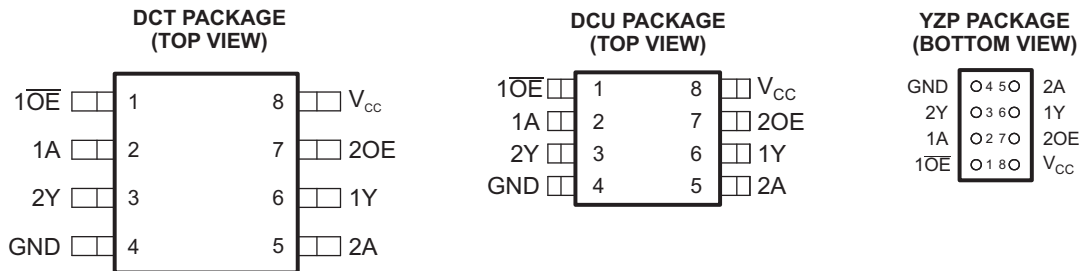


FEATURES

- Available in the Texas Instruments NanoFree™ Package
- Optimized for 1.8-V Operation and Is 3.6-V I/O Tolerant to Support Mixed-Mode Signal Operation
- I_{off} Supports Partial-Power-Down Mode Operation
- Sub-1-V Operable
- Max t_{pd} of 1.9 ns at 1.8 V
- Low Power Consumption, 10 μA at 1.8 V
- ±8-mA Output Drive at 1.8 V
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)



See mechanical drawings for dimensions.

DESCRIPTION/ORDERING INFORMATION

This dual buffer/driver is operational at 0.8-V to 2.7-V V_{CC}, but is designed specifically for 1.65-V to 1.95-V V_{CC} operation.

The SN74AUC2G241 is designed specifically to improve the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters.

The device is organized as two 1-bit line drivers with separate output-enable (1OE, 2OE) inputs. When 1OE is low or 2OE is high, the device passes data from the A inputs to the Y outputs. When 1OE is high or 2OE is low, the outputs are in the high-impedance state.

NanoFree™ package technology is a major breakthrough in IC packaging concepts, using the die as the package.

ORDERING INFORMATION

T _A	PACKAGE ⁽¹⁾		ORDERABLE PART NUMBER	TOP-SIDE MARKING ⁽²⁾
–40°C to 85°C	NanoFree™ – WCSP (DSBGA) 0.23-mm Large Bump – YZP (Pb-free)	Reel of 3000	SN74AUC2G241YZPR	__ _U2_
	SSOP – DCT	Reel of 3000	SN74AUC2G241DCTR	U41__ _
	VSSOP – DCU	Reel of 3000	SN74AUC2G241DCUR	U2_

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

(2) DCT: The actual top-side marking has three additional characters that designate the year, month, and assembly/test site.

DCU: The actual top-side marking has one additional character that designates the assembly/test site.

YZP: The actual top-side marking has three preceding characters to denote year, month, and sequence code, and one following character to designate the assembly/test site. Pin 1 identifier indicates solder-bump composition (1 = SnPb, • = Pb-free).



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

NanoFree is a trademark of Texas Instruments.

SN74AUC2G241

DUAL BUFFER/DRIVER WITH 3-STATE OUTPUTS

SCES535C–DECEMBER 2003–REVISED JANUARY 2007

DESCRIPTION/ORDERING INFORMATION (CONTINUED)

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor, and OE should be tied to GND through a pulldown resistor; the minimum value of the resistor is determined by the current-sinking/current-sourcing capability of the driver.

This device is fully specified for partial-power-down applications using I_{off} . The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

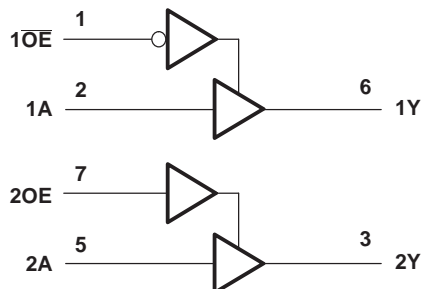
For more information about AUC Little Logic devices, please refer to the TI application report, *Applications of Texas Instruments AUC Sub-1-V Little Logic Devices*, literature number SCEA027.

FUNCTION TABLES

INPUTS		OUTPUT 1Y
1 \overline{OE}	1A	
L	H	H
L	L	L
H	X	Z

INPUTS		OUTPUT 2Y
2OE	2A	
H	H	H
H	L	L
L	X	Z

LOGIC DIAGRAM (POSITIVE LOGIC)



Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V_{CC}	Supply voltage range		–0.5	3.6	V
V_I	Input voltage range ⁽²⁾		–0.5	3.6	V
V_O	Voltage range applied to any output in the high-impedance or power-off state ⁽²⁾		–0.5	3.6	V
V_O	Output voltage range ⁽²⁾		–0.5	$V_{CC} + 0.5$	V
I_{IK}	Input clamp current	$V_I < 0$		–50	mA
I_{OK}	Output clamp current	$V_O < 0$		–50	mA
I_O	Continuous output current			±20	mA
	Continuous current through V_{CC} or GND			±100	mA
θ_{JA}	Package thermal impedance ⁽³⁾	DCT package		220	°C/W
		DCU package		227	
		YZP package		102	
T_{stg}	Storage temperature range		–65	150	°C

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) The package thermal impedance is calculated in accordance with JESD 51-7.

SN74AUC2G241

DUAL BUFFER/DRIVER

WITH 3-STATE OUTPUTS

SCES535C–DECEMBER 2003–REVISED JANUARY 2007

Recommended Operating Conditions⁽¹⁾

			MIN	MAX	UNIT
V _{CC}	Supply voltage		0.8	2.7	V
V _{IH}	High-level input voltage	V _{CC} = 0.8 V	V _{CC}		V
		V _{CC} = 1.1 V to 1.95 V	0.65 × V _{CC}		
		V _{CC} = 2.3 V to 2.7 V	1.7		
V _{IL}	Low-level input voltage	V _{CC} = 0.8 V	0		V
		V _{CC} = 1.1 V to 1.95 V	0.35 × V _{CC}		
		V _{CC} = 2.3 V to 2.7 V	0.7		
V _I	Input voltage		0	3.6	V
V _O	Output voltage	Active state	0	V _{CC}	V
		3-state	0	3.6	
I _{OH}	High-level output current	V _{CC} = 0.8 V	−0.7		mA
		V _{CC} = 1.1 V	−3		
		V _{CC} = 1.4 V	−5		
		V _{CC} = 1.65 V	−8		
		V _{CC} = 2.3 V	−9		
I _{OL}	Low-level output current	V _{CC} = 0.8 V	0.7		mA
		V _{CC} = 1.1 V	3		
		V _{CC} = 1.4 V	5		
		V _{CC} = 1.65 V	8		
		V _{CC} = 2.3 V	9		
Δt/Δv	Input transition rise or fall rate	V _{CC} = 0.8 V to 1.65 V ⁽²⁾	20		ns/V
		V _{CC} = 1.65 V to 1.95 V ⁽³⁾	20		
		V _{CC} = 2.3 V to 2.7 V ⁽³⁾	20		
T _A	Operating free-air temperature		−40	85	°C

(1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

(2) The data was taken at C_L = 15 pF, R_L = 2 kΩ (see [Figure 1](#)).

(3) The data was taken at C_L = 30 pF, R_L = 500 Ω (see [Figure 1](#)).

Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V _{CC}	MIN	TYP ⁽¹⁾	MAX	UNIT
V _{OH}		I _{OH} = −100 μA	0.8 V to 2.7 V	V _{CC} − 0.1			V
		I _{OH} = −0.7 mA	0.8 V	0.55			
		I _{OH} = −3 mA	1.1 V	0.8			
		I _{OH} = −5 mA	1.4 V	1			
		I _{OH} = −8 mA	1.65 V	1.2			
		I _{OH} = −9 mA	2.3 V	1.8			
V _{OL}		I _{OL} = 100 μA	0.8 V to 2.7 V			0.2	V
		I _{OL} = 0.7 mA	0.8 V	0.25			
		I _{OL} = 3 mA	1.1 V			0.3	
		I _{OL} = 5 mA	1.4 V			0.4	
		I _{OL} = 8 mA	1.65 V			0.45	
		I _{OL} = 9 mA	2.3 V			0.6	
I _I	All inputs	V _I = V _{CC} or GND	0 to 2.7 V			±5	μA
I _{off}		V _I or V _O = 2.7 V	0			±10	μA
I _{OZ}		V _O = V _{CC} or GND	2.7 V			±10	μA
I _{CC}		V _I = V _{CC} or GND, I _O = 0	0.8 V to 2.7 V			10	μA
C _I		V _I = V _{CC} or GND	2.5 V	2.5			pF
C _O		V _O = V _{CC} or GND	2.5 V	5.5			pF

(1) All typical values are at T_A = 25°C.

Switching Characteristics

over recommended operating free-air temperature range, C_L = 15 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 0.8 V	V _{CC} = 1.2 V ± 0.1 V		V _{CC} = 1.5 V ± 0.1 V		V _{CC} = 1.8 V ± 0.15 V			V _{CC} = 2.5 V ± 0.2 V		UNIT
			TYP	MIN	MAX	MIN	MAX	MIN	TYP	MAX	MIN	MAX	
t _{pd}	A	Y	5.1	1	3.5	0.8	2.3	0.7	1.2	1.9	0.6	1.4	ns
t _{en}	$\overline{\text{OE}}$ or OE	Y	5.9	1.2	4.2	1	2.7	0.9	1.3	2	0.8	1.6	ns
t _{dis}	$\overline{\text{OE}}$ or OE	Y	6.2	2.2	4.8	2.5	4.4	1	2.9	4.2	1.6	3.3	ns

Switching Characteristics

over recommended operating free-air temperature range, C_L = 30 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 1.8 V ± 0.15 V			V _{CC} = 2.5 V ± 0.2 V		UNIT
			MIN	TYP	MAX	MIN	MAX	
t _{pd}	A	Y	0.9	1.6	2.5	0.8	1.8	ns
t _{en}	$\overline{\text{OE}}$ or OE	Y	1.1	1.7	2.8	1	2	ns
t _{dis}	$\overline{\text{OE}}$ or OE	Y	1.9	2.3	3.6	0.9	2.1	ns

SN74AUC2G241

DUAL BUFFER/DRIVER

WITH 3-STATE OUTPUTS

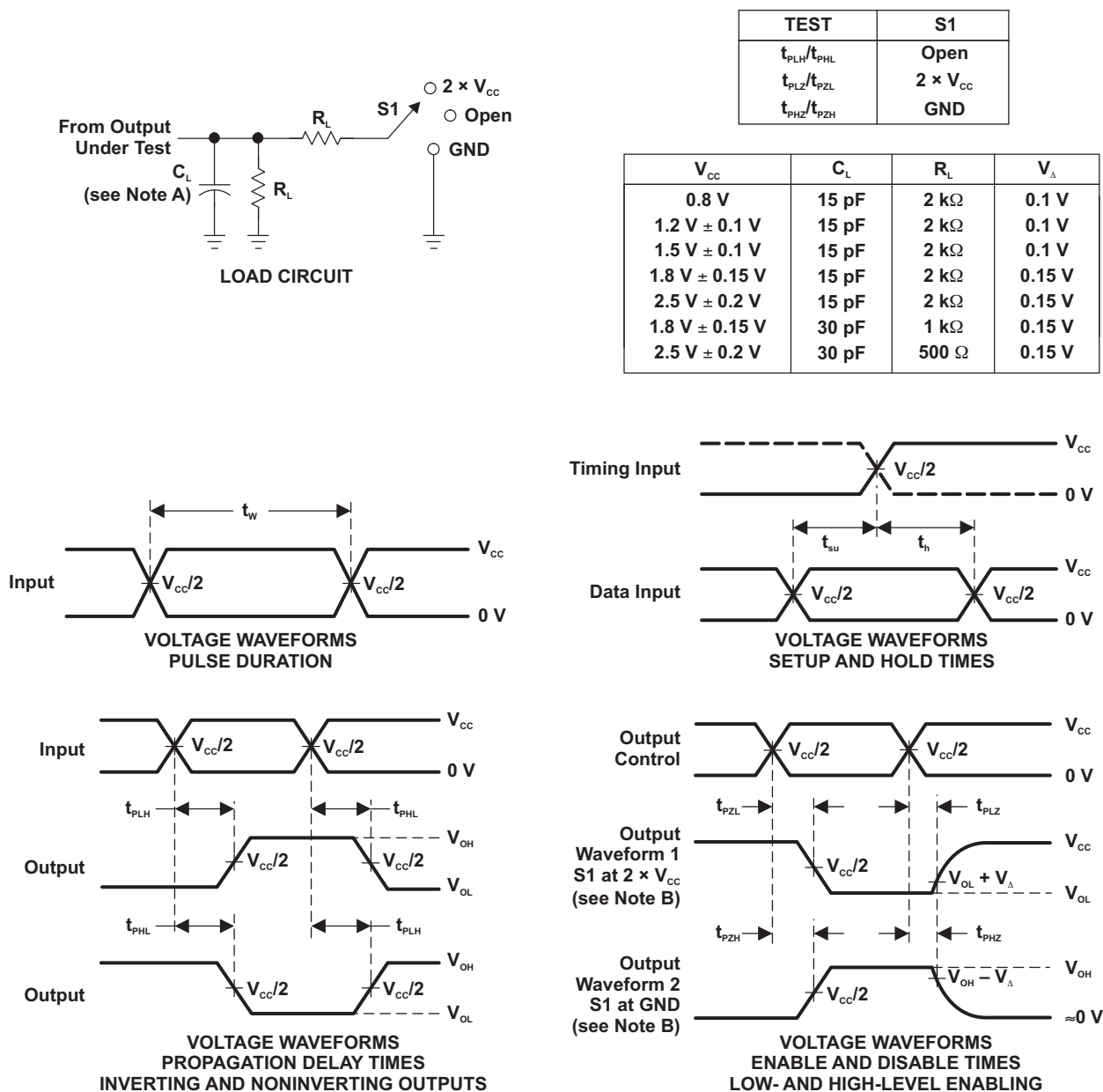
SCES535C–DECEMBER 2003–REVISED JANUARY 2007

Operating Characteristics

$T_A = 25^\circ\text{C}$

PARAMETER		TEST CONDITIONS	$V_{CC} = 0.8\text{ V}$	$V_{CC} = 1.2\text{ V}$	$V_{CC} = 1.5\text{ V}$	$V_{CC} = 1.8\text{ V}$	$V_{CC} = 2.5\text{ V}$	UNIT
			TYP	TYP	TYP	TYP	TYP	
C_{pd}	Power dissipation capacitance	$f = 10\text{ MHz}$	16	16	16	17	18	pF

PARAMETER MEASUREMENT INFORMATION



- NOTES:
- C_L includes probe and jig capacitance.
 - Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_o = 50 \Omega$, slew rate \geq 1 V/ns.
 - The outputs are measured one at a time, with one transition per measurement.
 - t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - t_{PZL} and t_{PZH} are the same as t_{en} .
 - t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74AUC2G241DCTR	ACTIVE	SM8	DCT	8	3000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	U41 (R, Z)	Samples
SN74AUC2G241DCUR	ACTIVE	VSSOP	DCU	8	3000	RoHS & Green	NIPDAU SN	Level-1-260C-UNLIM	-40 to 85	(U41Q, U41R)	Samples
SN74AUC2G241YZPR	ACTIVE	DSBGA	YZP	8	3000	RoHS & Green	SNAGCU	Level-1-260C-UNLIM	-40 to 85	U2N	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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TAPE AND REEL INFORMATION



*All dimensions are nominal

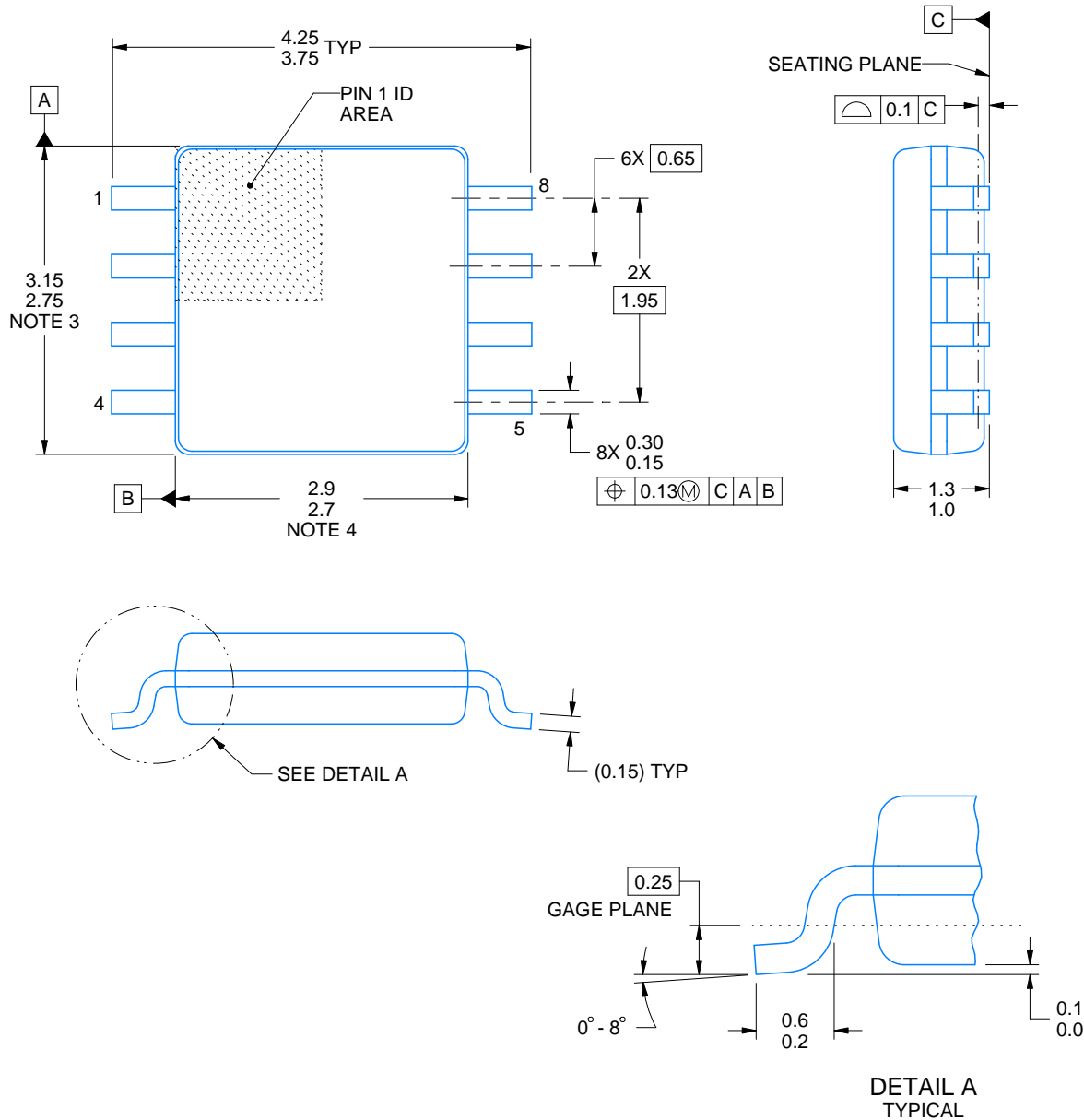
Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AUC2G241DCTR	SM8	DCT	8	3000	177.8	12.4	3.45	4.4	1.45	4.0	12.0	Q3
SN74AUC2G241DCTR	SM8	DCT	8	3000	180.0	13.0	3.35	4.5	1.55	4.0	12.0	Q3
SN74AUC2G241DCUR	VSSOP	DCU	8	3000	178.0	9.5	2.25	3.35	1.05	4.0	8.0	Q3
SN74AUC2G241DCUR	VSSOP	DCU	8	3000	180.0	8.4	2.25	3.35	1.05	4.0	8.0	Q3
SN74AUC2G241YZPR	DSBGA	YZP	8	3000	178.0	9.2	1.02	2.02	0.63	4.0	8.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AUC2G241DCTR	SM8	DCT	8	3000	183.0	183.0	20.0
SN74AUC2G241DCTR	SM8	DCT	8	3000	182.0	182.0	20.0
SN74AUC2G241DCUR	VSSOP	DCU	8	3000	202.0	201.0	28.0
SN74AUC2G241DCUR	VSSOP	DCU	8	3000	202.0	201.0	28.0
SN74AUC2G241YZPR	DSBGA	YZP	8	3000	220.0	220.0	35.0



4220784/B 07/2020

NOTES:

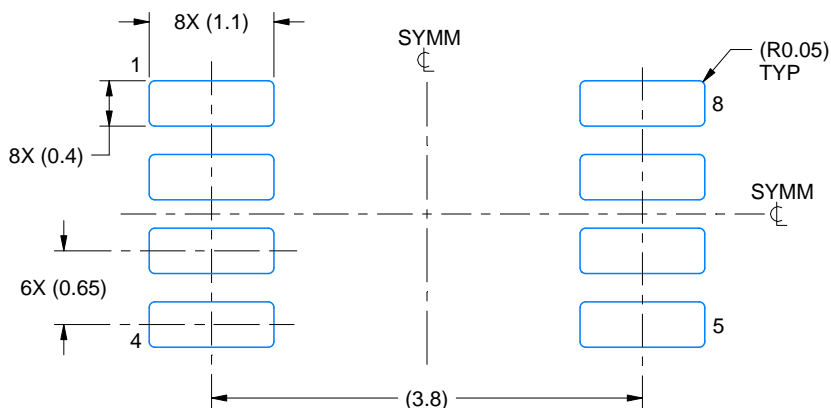
1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MS-187.

EXAMPLE BOARD LAYOUT

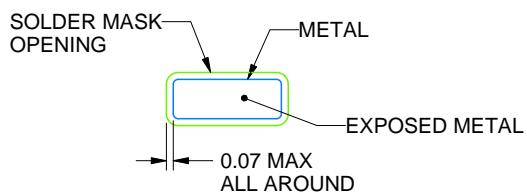
DCT0008A

SSOP - 1.3 mm max height

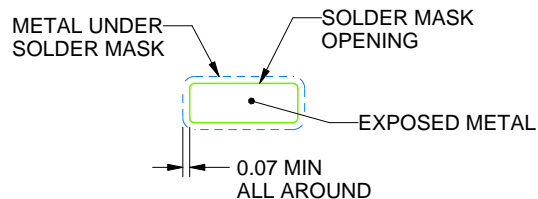
SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:15X



NON SOLDER MASK
DEFINED



SOLDER MASK
DEFINED

SOLDER MASK DETAILS

4220784/B 07/2020

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

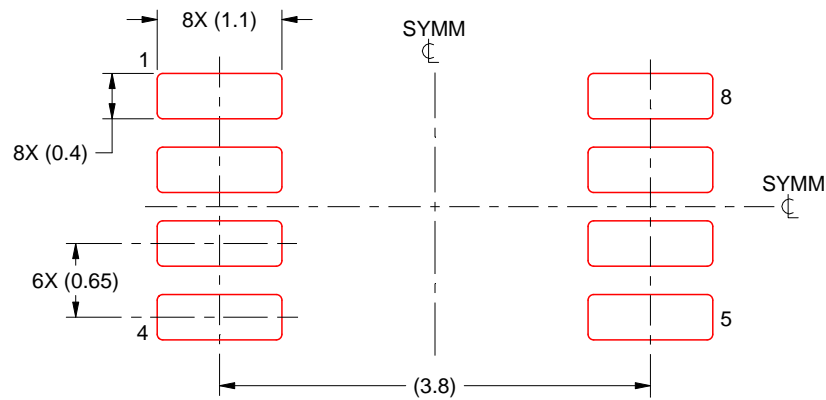
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DCT0008A

SSOP - 1.3 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:15X

4220784/B 07/2020

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

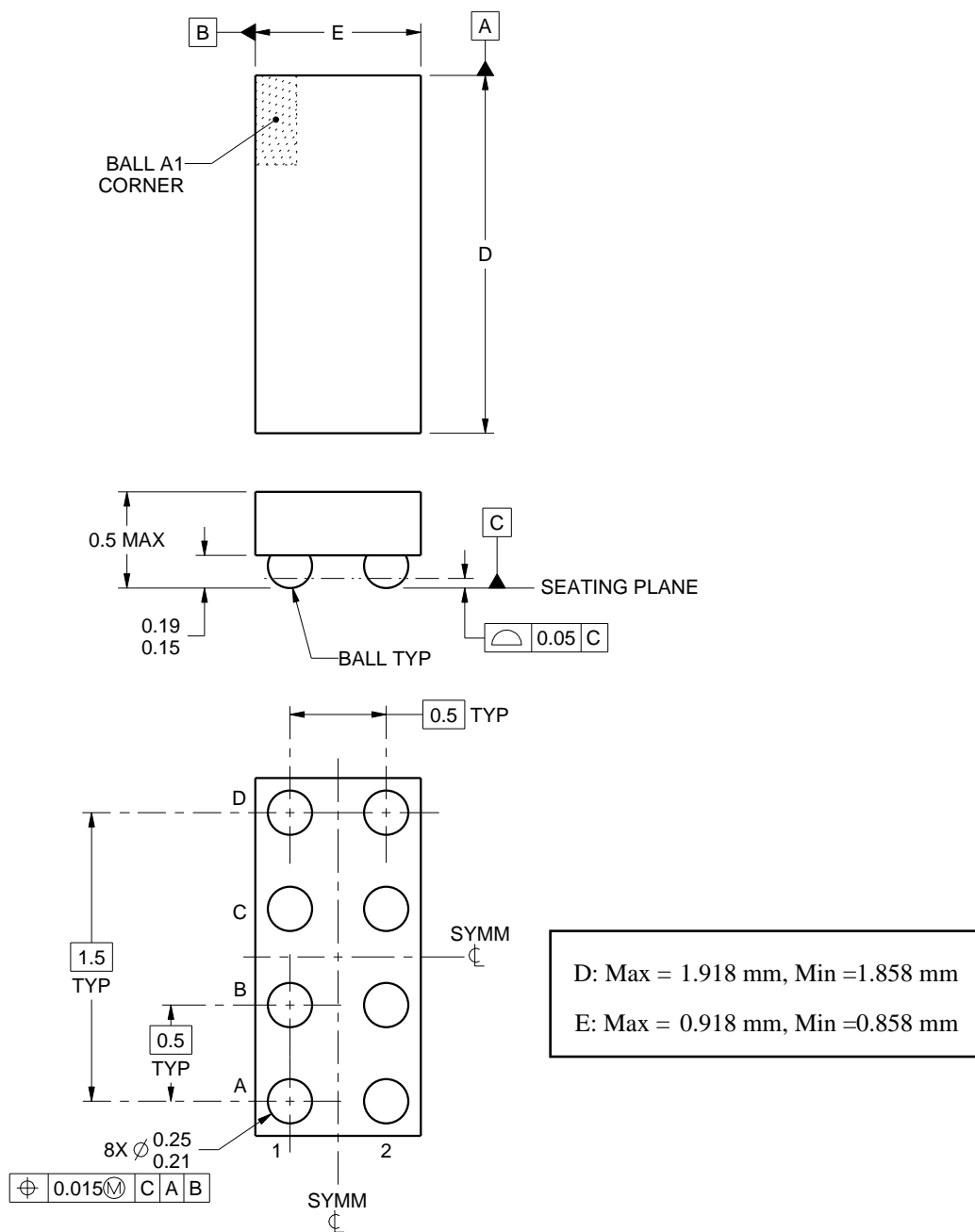
YZP0008



PACKAGE OUTLINE

DSBGA - 0.5 mm max height

DIE SIZE BALL GRID ARRAY



4223082/A 07/2016

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.

EXAMPLE BOARD LAYOUT

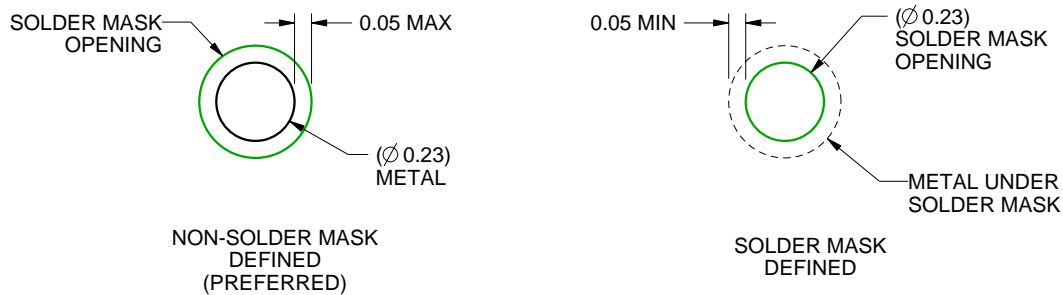
YZP0008

DSBGA - 0.5 mm max height

DIE SIZE BALL GRID ARRAY



LAND PATTERN EXAMPLE
SCALE:40X



SOLDER MASK DETAILS
NOT TO SCALE

4223082/A 07/2016

NOTES: (continued)

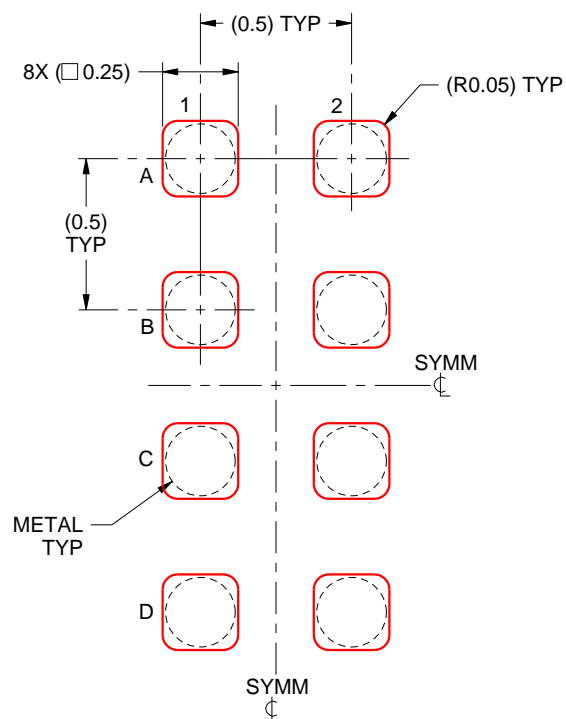
- Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints. For more information, see Texas Instruments literature number SNVA009 (www.ti.com/lit/snva009).

EXAMPLE STENCIL DESIGN

YZP0008

DSBGA - 0.5 mm max height

DIE SIZE BALL GRID ARRAY



SOLDER PASTE EXAMPLE
BASED ON 0.1 mm THICK STENCIL
SCALE:40X

4223082/A 07/2016

NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.

DCU (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE (DIE DOWN)



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
 - D. Falls within JEDEC MO-187 variation CA.

DCU (S-PDSO-G8)

PLASTIC SMALL OUTLINE PACKAGE (DIE DOWN)



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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